MC145407

Advance Information **5 Volt Only Driver/Receiver** EIA–232–E and CCITT V.28

The MC145407 is a silicon–gate CMOS IC that combines three drivers and three receivers to fulfill the electrical specifications of EIA–232–E and CCITT V.28 while operating from a single + 5 V power supply. A voltage doubler and inverter convert the + 5 V to \pm 10 V. This is accomplished through an on–board 20 kHz oscillator and four inexpensive external electrolytic capacitors. The three drivers and three receivers of the MC145407 are virtually identical to those of the MC145406. Therefore, for applications requiring more than three drivers and/or three receivers, an MC145406 can be powered from an MC145407, since the MC145407 charge pumps have been designed to guarantee \pm 5 V at the output of up to six drivers. Thus, the MC145407 provides a high–performance, low–power, stand–alone solution or, with the MC145406, a + 5 V only, high–performance two–chip solution.

Drivers

- \pm 7.5 V Output Swing
- 300 Ω Power–Off Impedance
- Output Current Limiting
- TTL and CMOS Compatible Inputs
- Slew Rate Range Limited from 4 V/μs to 30 V/μs

Receivers

- + 25 V Input Range
- 3 to 7 kΩ Input Impedance
- 0.8 V Hysteresis for Enhanced Noise Immunity

Charge Pumps

- + 5 V to ± 10 V Dual Charge Pump Architecture
- Supply Outputs Capable of Driving Three On–Chip Drivers and Three Drivers on the MC145406 Simultaneously
- Requires Four Inexpensive Electrolytic Capacitors
- On–Chip 20 kHz Oscillator





This document contains information on a new product. Specifications and information herein are subject to change without notice.



REV 1 10/95

FUNCTION DIAGRAM





MAXIMUM RATINGS (Voltage polarities referenced to GND)

Rating	Symbol	Value	Unit
DC Supply Voltages	Vcc	– 0.5 to + 6.0	V
Input Voltage Range Rx1 – Rx3 Inputs DI1 – DI3 Inputs	VIR	V _{SS} – 15 to V _{DD} + 15 – 0.5 to (V _{CC} + 0.5)	V
DC Current per Pin	I	± 100	mA
Power Dissipation	PD	1	W
Operating Temperature Range	TA	– 40 to + 85	°C
Storage Temperature Range	T _{stg}	– 85 to + 150	°C

This device contains protection circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit. For proper operation, it is recommended that the voltages at the DI and DO pins be constrained to the range GND \leq V_{DI} \leq V_{CC} and GND \leq V_{DO} \leq V_{CC}. Also, the voltage at the Rx pin should be constrained to (V_{SS} – 15 V) \leq V_{RX1} – Rx3 \leq (V_{DD} + 15 V), and Tx should be constrained to V_{SS} \leq V_{TX1} – Tx3 \leq V_{DD}.

Unused inputs must always be tied to appropriate logic voltage level (e.g., GND or V_{CC} for DI, and GND for Rx).

DC ELECTRICAL CHARACTERISTICS (All polarities referenced to GND = 0 V; C1, C2, C3, C4 = 10 μ F; T_A = -40 to + 85°C)

Parameter	Symbol	Min	Тур	Max	Unit
DC Supply Voltage	VCC	4.5	5	5.5	V
Quiescent Supply Current (Outputs unloaded, inputs low)	ICC	—	1.2	3.0	mA
Output Voltage $I_{load} = 0 \text{ mA}$ $I_{load} = 5 \text{ mA}$ $I_{load} = 10 \text{ mA}$	V _{DD}	8.5 7.5 6	10 9.5 9	11 — —	V
I _{load} = 0 mA I _{load} = 5 mA I _{load} = 10 mA	V _{SS}	- 8.5 - 7.5 - 6	- 10 - 9.2 - 8.6	-11 	

RECEIVER ELECTRICAL SPECIFICATIONS

(Voltage polarities referenced to GND = 0 V; V_{CC} = + 5 V \pm 10%; C1, C2, C3, C4 = 10 μ F; T_A = - 40 to + 85°C)

Characteristic		Symbol	Min	Тур	Max	Unit
Input Turn–on Threshold VDO1 – DO3 = VOL	Rx1 – Rx3	V _{on}	1.35	1.8	2.35	V
Input Turn–off Threshold VDO1 – DO3 = VOH	Rx1 – Rx3	V _{off}	0.75	1.0	1.25	V
Input Threshold Hysteresis (Von - Voff)	Rx1 – Rx3	V _{hys}	0.6	0.8	—	V
Input Resistance	Rx1 – Rx3	R _{in}	3.0	5.4	7.0	kΩ
High–Level Output Voltage $V_{Rx1 - Rx3} = -3 V \text{ to} - 25 V$ $I_{OH} = -20 \mu A$ $I_{OH} = -1 mA$	DO1 – DO3	VOH	V _{CC} - 0.1 V _{CC} - 0.7	 4.3		V
Low-Level Output Voltage $V_{Rx1} - R_{x3} = + 3 V \text{ to } + 25 V$ $I_{OL} = + 20 \mu A$ $I_{OL} = + 1.6 \text{ mA}$	DO1 – DO3	V _{OL}		0.01 0.5	0.1 0.7	V

DRIVER ELECTRICAL SPECIFICATIONS

(Voltage polarities referenced to GND = 0 V: V_{CC} = +5 V ±10%; C1, C2, C3, C4 = 10 μ F; T_A = -40 to +85°C)

Characteristic			Min	Тур	Max	Unit
Digital Input Voltage Logic 0 Logic 1	DI1 – DI3	VIL VIH	 2.0		0.8	V
Input Current GND \leq VDI1 – DI3 \leq VCC	DI1 – DI3	l _{in}	_	_	± 1.0	μΑ
Output High Voltage $V_{DI1 - DI3}$ = Logic 0, RL = 3.0 k Ω	Tx1 – Tx3 Tx1 – Tx6*	VOH	6 5	7.5 6.5	_	V
Output Low Voltage $V_{DI1 - DI3}$ = Logic 1, RL = 3.0 k Ω	Tx1 – Tx3 Tx1 – Tx6*	VOL	- 6 - 5	- 7.5 - 6.5		V
Off Source Impedance (Figure 1)	Tx1 – Tx3	Z _{off}	300	_	—	Ω
Output Short–Circuit Current V _{CC} = + 5.5 V	$\label{eq:transform} \begin{array}{c} Tx1-Tx3\\ Tx1-Tx3 \text{ shorted to } GND^{**}\\ Tx1-Tx3 \text{ shorted to } \pm 15 \text{ V}^{***} \end{array}$	ISC			± 60 ± 100	mA

* Specifications for an MC145407 powering an MC145406 with three additional drivers/receivers.

** Specification is for one Tx output pin to be shorted at a time. Should all three driver outputs be shorted simultaneously, device power dissipation limits could be exceeded.

*** This condition could exceed package limitations.

SWITCHING CHARACTERISTICS ($V_{CC} = +5 V \pm 10\%$; C1, C2, C3, C4 = 10 µF; T_A = -40 to + 85°C; See Figures 2 and 3)

Characteristic		Symbol	Min	Тур	Max	Unit
Drivers						
Propagation Delay Time Low-to-High	Tx1 – Tx3	^t PLH				μs
$R_L = 3 k\Omega$, $C_L = 50 pF$ or 2500 pF			_	0.5	1	
High–to–Low R _L = 3 k Ω , C _L = 50 pF or 2500 pF		^t PHL	_	0.5	1	
Output Slew Rate Minimum Load: R _L = 7 kΩ, C _L = 0 pF	Tx1 – Tx3	SR	_	9.0	±30	V/µs
Maximum Load: $R_L = 3 \text{ k}\Omega$, $C_L = 2500 \text{ pF}$			4.0	_	—	
Receivers (C _L = 50 pF)						

Propagation Delay Time	DO1 – DO3					μs
Low-to-High		^t PLH	_	_	1	
High-to-Low		^t PHL	_	_	1	
Output Rise Time	DO1 – DO3	tr	_	250	400	ns
Output Fall Time	DO1 – DO3	t _f	_	40	100	ns



Figure 1. Power–Off Source Resistance



RECEIVERS







Figure 3. Slew Rate Characterization

PIN DESCRIPTIONS

VCC Digital Power Supply (Pin 19)

The digital supply pin, which is connected to the logic power supply. This pin should have a 0.33 μF capacitor to ground.

GND

Ground (Pin 2)

Ground return pin is typically connected to the signal ground pin of the EIA–232–E connector (Pin 7) as well as to the logic power supply ground.

VDD

Positive Power Supply (Pin 17)

This is the positive output of the on-chip voltage doubler and the positive power supply input of the driver/receiver sections of the device. This pin requires an external storage capacitor to filter the 50% duty cycle voltage generated by the charge pump.

Vss

Negative Power Supply (Pin 4)

This is the negative output of the on-chip voltage doubler/ inverter and the negative power supply input of the driver/receiver sections of the device. This pin requires an external storage capacitor to filter the 50% duty cycle voltage generated by the charge pump.

C2+, C2-, C1-, C1+

Voltage Doubler and Inverter (Pins 1, 3, 18, 20)

These are the connections to the internal voltage doubler and inverter, which generate the V_{DD} and V_{SS} voltages.

Rx1, Rx2, Rx3

Receive Data Input (Pins 5, 7, 9)

These are the EIA–232–E receive signal inputs. A voltage between + 3 and + 25 V is decoded as a space and causes the corresponding DO pin to swing to ground (0 V). A voltage between – 3 and – 25 V is decoded as a mark, and causes the DO pin to swing up to V_{CC}.

DO1, DO2, DO3

Data Output (Pins 16, 14, 12)

These are the receiver digital output pins, which swing from V_{CC} to GND. Each output pin is capable of driving one LSTTL input load.

DI1, DI2, DI3

Data Input (Pins 15, 13, 11)

These are the high impedance digital input pins to the drivers. Input voltage levels on these pins must be between V_{CC} and GND.

Tx1, Tx2, Tx3

Transmit Data Output (Pins 6, 8, 10)

These are the EIA–232–E transmit signal output pins, which swing toward V_{DD} and V_{SS}. A logic 1 at a DI input causes the corresponding Tx output to swing toward V_{SS}. A logic 0 causes the output to swing toward V_{DD}. The actual levels and slew rate achieved will depend on the output loading (R_L \parallel C_L).

APPLICATIONS INFORMATION

ESD CONSIDERATIONS

ESD protection on IC devices that have their pins accessible to the outside world is essential. High static voltages applied to the pins when someone touches them either directly or indirectly can cause damage to gate oxides and transistor junctions by coupling a portion of the energy from the I/O pin to the power supply busses of the IC. This coupling will usually occur through the internal ESD protection diodes. The key to protecting the IC is to shunt as much of the energy to ground as possible before it enters the IC. Figure 7 shows a technique which will clamp the ESD voltage at approximately + 15 V using the MMBZ15VDLT1. Any residual voltage which appears on the supply pins is shunted to ground through the 0.1 μ F capacitors.

OPERATION WITH SMALLER VALUE CHARGE PUMP CAPS

The MC145407 is characterized in the electrical tables

using 10 μ F charge pump caps to illustrate its capability in driving a companion MC145406 or MC145403. If there is no requirement to support a second interface device and/or the charge pump is not being used to power any other components, the MC145407 is capable of complying with EIA–232–E and V.28 with smaller value charge pump caps. Table 1 summarizes driver performance with both 2.2 μ F and 1.0 μ F charge pump caps.

Parameter	2.2 μ F	1.0 μF
Tx V _{OH} @ 25°C	7.3	7.2
Tx V _{OH} @ 85°C	7.2	7.1
Tx V _{OL} @ 25°C	- 6.5	- 6.4
Tx V _{OL} @ 85°C	- 6.1	- 6.0
Tx Slew Rate @ 25°C	8.0 V/μs	8.0 V/μs
Tx Slew Rate @ 85°C	7.0 V/μs	7.0 V/μs



Figure 4. 5 V, 300 Baud Modem with EIA-232-E Interface



Figure 5. MC145406/MC145407 5 V Only Solution for up to Six EIA-232-E Drivers and Receivers



Figure 6. Two Supply Configuration (MC145407 Generates VSS Only)



Figure 7. ESD Protection Scheme

PACKAGE DIMENSIONS

P SUFFIX PLASTIC DIP CASE 738–03

DW SUFFIX



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

 DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	1.010	1.070	25.66	27.17
В	0.240	0.260	6.10	6.60
С	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54	BSC
J	0.008	0.015	0.21	0.38
ĸ	0.110	0.140	2.80	3.55
L	0.300	BSC	7.62 BSC	
М	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01



NOTES: 1. DIMENSIONING AND TOLERANCING PER

ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS A AND B DO NOT INCLUDE

MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.150

(0.006) PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	12.65	12.95	0.499	0.510
В	7.40	7.60	0.292	0.299
С	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
Μ	0 °	7 °	0 °	7 °
Р	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

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